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SHEET 1 OF 1

EXAMINER'S INITIALS		CITE NO.	DOCUMENT NO.	DATE	NAME	Complete if Known		FILING DATE (if appropriate)
						APPLICATION NUMBER	22126.0005U1	
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						FIRST NAMED INVENTOR	Jianhua Yin	
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						EXAMINER NAME	Unassigned	

EXAMINER'S INITIALS	CITE NO.	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)

EXAMINER'S INITIALS	CITE NO.	FOREIGN PATENT DOCUMENT Country Code-Number-Kind Code	DATE	NAME	TRANSLATION Yes/No
MCU	B1	EP0602261	22/06/94	Sliwa, Jr., et al.	No
MCU	B2	JP06038297	19/04/94	Narendora Sangubi	Yes

EXAMINER'S INITIALS	CITE NO.	NON-PATENT CITATIONS (Include Author, Title, Publisher, Relevant Pages, Date and Place of Publication)
MCU	B3	Article entitled "Interdigital Pair Bonding for High Frequency (20-50 MHz) Ultrasonic Composite Transducers" by Ruibin Liu, Kasia A. Harasiewicz and F. Stuart Foster, Printed in the IEEE Transaction on Ultrasonics, Ferroelectrics, and Frequency Control, Volume 48, No. 1, January 2001.
MCU	B4	Article entitled "2-2 Piezoelectric Composites with High Density and Fine Sale Fabricated by Interdigital Pair Bonding" by Ruibin Liu, Kasia A. Harasiewicz, D. Knapik, N.A. Freeman and F. Stuart Foster, Printed in the Applied Physics Letters, Volume 75, No. 21, 22 November 1999.
MCU	B5	Article entitled "Fabrication of 2-2 Piezoelectric Composites by Interdigital Pair Bonding" by Ruibin Liu, Donald Knapik, Kasia A. Harasiewicz and F. Stuart Foster, Printed in the 1999 IEEE Ultrasonic Symposium, 1999.

EXAMINER SIGNATURE: <u>Mayra</u>	DATE CONSIDERED: <u>6/20/05</u>
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	